SOT−89, 5 LEAD
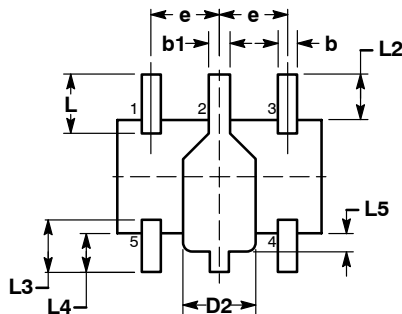CASE 528AB
ISSUE O

DATE 23 NOV 2009

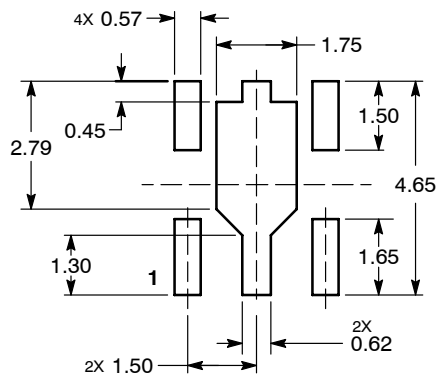**SCALE 2:1**
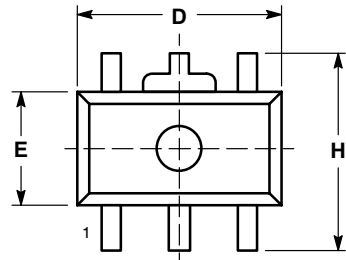
TOP VIEW
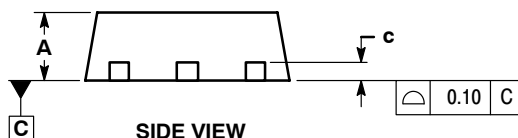
**SIDE VIEW**

BOTTOM VIEW

**RECOMMENDED
MOUNTING FOOTPRINT***

DIMENSIONS: MILLIMETERS

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS INCLUDES LEAD FINISH.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. DIMENSIONS L, L2, L3, L4, L5, AND H ARE MEASURED AT DATUM PLANE C.

DIM	MILLIMETERS	
	MIN	MAX
A	1.40	1.60
b	0.32	0.52
b1	0.37	0.57
c	0.30	0.50
D	4.40	4.60
D2	1.40	1.80
E	2.40	2.60
e	1.40	1.60
H	4.25	4.45
L	1.10	1.50
L2	0.80	1.20
L3	0.95	1.35
L4	0.65	1.05
L5	0.20	0.60

**GENERIC
MARKING DIAGRAM***

XXX
XMM
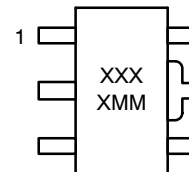
XXXX = Specific Device Code
MM = Lot Number
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G", may or not be present.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON47037E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOT−89, 5 LEAD	PAGE 1 OF 1